

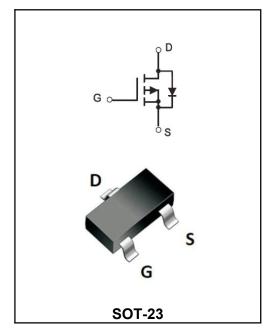
-40V P-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

I _D	-3A	
V _{DSS}	-40V	
R _{DSON} -typ(@V _{GS} =-10V)	< 75mΩ (Type:62 mΩ)	

Application

- **♦**Battery protection
- **♦**Load switch
- ♦Uninterruptible power supply



Marking Code				
YFW3P04A	3P04A			

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V _{DS}	-40	V
Gate - Source Voltage	V _{GS}	±20	V
Continuous Drain Current, V _{GS} @ -4.5V ¹ @T _A =25℃	I _D	-3.7	А
Continuous Drain Current, V _{GS} @ -4.5V ¹ @T _A =70℃	I _D	-3.0	A
Pulsed Drain Current ²	I _{DM}	-16.1	A
Total Power Dissipation³ @T _A =25℃	P _D	1.32	w
Total Power Dissipation³ @T _A =70°C	P _D	0.84	w
Storage Temperature Range	T _{STG}	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	R _{0JA}	125	°C/W
Thermal Resistance Junction-Ambient ¹ (t≤10s)	R _{0JA}	95	°C/W
Thermal Resistance Junction to Case ¹	R _{eJC}	80	°C/W





Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Тур	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	BV _{DSS}	-40	-44	-	V
BV _{DSS} Temperature Coefficient	Reference to 25℃, I _D =-1mA	∆BV _{DSS/∆TJ}	-	-0.018	-	V/°C
Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-3A	V _{GS} =-10V, I _D =-3A R _{DS(ON)}		62	75	mΩ
	V _{GS} =-4.5V, I _D =-2A		-	81	100	
Gate -Threshold Voltage	V V I 050 A	V _{GS(th)}	-1.0	-1.5	-2.5	V
V _{GS} (th) Temperature Coefficient	$V_{DS}=V_{GS}$, $I_D=-250uA$	△V _{GS(th)}	-	2.5	-	mV/°C
Duelle Course la classe Course	V _{DS} =-40V , V _{GS} =0V , T _J =25℃		-	-	-1	μΑ
Drain-Source Leakage Current	V _{DS} =-40V , V _{GS} =0V , T _J =55℃	l _{DSS} -	-	-	-5	
Gate –Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Forward Transconductance	V _{DS} =-5V , I _D =-3V	g _{fs}	-	5.8	-	S
Total Gate Charge(-4.5V)	V = 22V	Qg	-	6.4	-	
Gate-Source Charge	V _{DS} =-32V V _{GS} =-4.5V	Q _{gs}	-	2.1	-	nC
Gate-Drain Charge	I _D =-3A	Q_{gd}	-	2.5	-	1
Turn-on delay time		t _{d(on)}	-	4.2	-	
Rise Time	$V_{DD} = -20V$ $V_{GS} = -4.5V$	Tr	-	23	-	
Turn-Off Delay Time	I_D = -3A R_G =3.3 Ω	t _{d(OFF)}	-	26.8	-	- ns
Fall Time	- K _G −3.3Ω	t _f	-	20.6	-	
Input Capacitance	- V _{DS} =-15V	C _{iss}	-	620	-	
Output Capacitance	V _{GS} =0V	Coss	-	65	-	PF
Reverse Transfer Capacitance	f=1MHz	C _{rss}	-	53	-	1
Continuous Source Current ^{1.4}	V V 0V	Is	-	-	-3.2	Α
Pulsed Source Current ^{2.4}	$V_G=V_D=0V$, Force Current	I _{SM}	-	-	-16.1	Α
Diode Forward Voltage ²	V_{GS} =0 V , I_{S} =-1 A , T_{J} =25 $^{\circ}$ C	V _{SD}	-	-	-1	V

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%$
- $3 {\scriptstyle \smallsetminus}$ The power dissipation is limited by $150 {\, ^\circ \! \rm C}$ junction temperature
- 4. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Ratings and Characteristic Curves

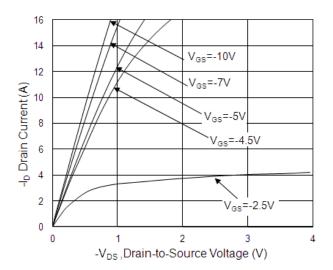


Fig.1 Typical Output Characteristics

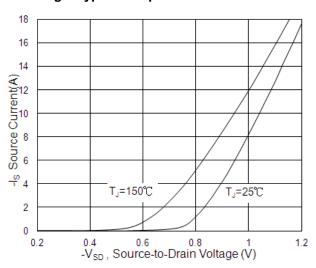


Fig.3 Forward Characteristics Of Reverse

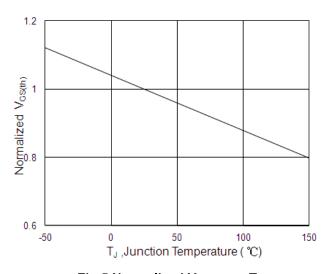


Fig.5 Normalized $V_{GS(th)}$ vs. $T_{\text{NCe.}}$

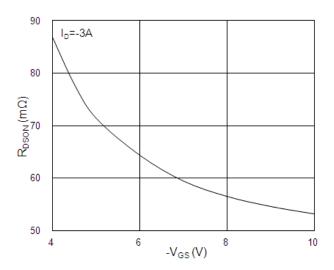


Fig.2 On-Resistance vs. G-S Voltage

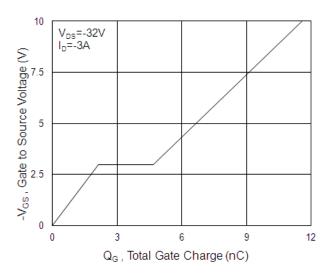


Fig.4 Gate-Charge Characteristics

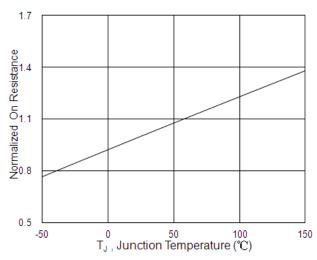
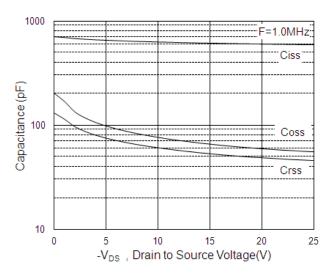


Fig.6 Normalized RDSON vs. TJ



Ratings and Characteristic Curves



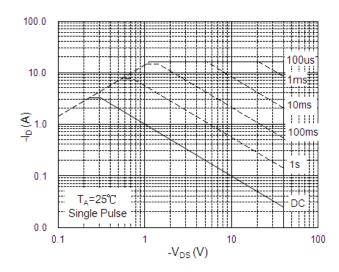


Fig.7 Capacitance



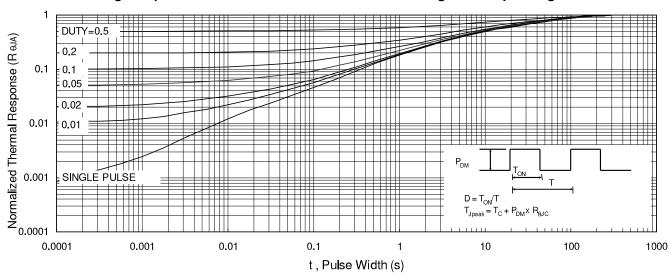
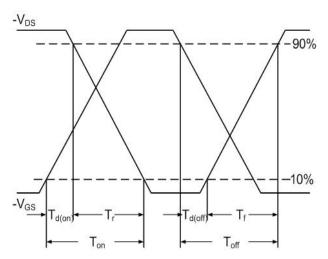
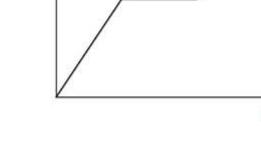


Fig.9 Normalized Maximum Transient Thermal Impedance

-VGS

4.5V





Qgs

Qg

Qgd

Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

Charge

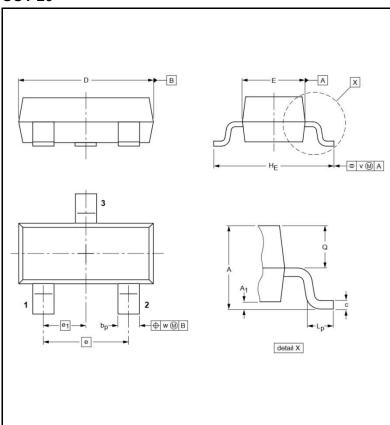


Ordering information

Package	Package Packing Description		Packing Quantity	
SOT-23	Tape/Reel,7"reel	3000pcs/Reel	24000PCS/Box 120000PCS/Carton	

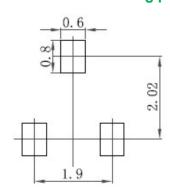
Package Dimensions

SOT-23



Dim.	Millimeter (mm)		mi	il
	Min.	Max.	Min.	Max.
Α	0.9	1.15	35	45
A1	0	.1	3.9)
bp	0.38	0.48	15	19
С	0.09	0.15	3.54	5.9
D	2.8	3.0	110	118
Е	1.2	1.4	47	55
Е	1.9		75	
E1	0.95		37	,
HE	2.1	2.55	83	100
Lp	0.15	0.45	5.9	18
Q	0.45	0.55	18	22
V	0.2		7.9	
W	0.1		4	

The recommended mounting pad size





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